

## News Release

### For Immediate Release

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**Contact:** Roger Dullinger, Marketing Communications Manager  
(952) 469-8278, [Roger.Dullinger@itweae.com](mailto:Roger.Dullinger@itweae.com)

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## MPM Introduces Next Generation Momentum II Printer

Lakeville, Minnesota, November 5, 2019 – ITW EAE is introducing the MPM® Momentum II™ Printer as the next generation of the highly successful Momentum printer line. The Momentum II features a new set of enhanced technologies that bring further advancement in quality, yield, productivity, ease of use and flexibility.

The Momentum II features a newly designed cover set with a larger window and wider access inside the printer. The quick-release squeegee makes changing blades quick and easy with no tools required. It takes less than 30 seconds to change the blade. A new patent-pending jar dispenser is available in addition to the standard cartridge dispenser. The operating software has been upgraded to Windows 10 and has new production tools and QuickStart™ programming that make it even more powerful and easier to use.

One of the key new features available for the Momentum II is a new paste management system that provides innovative tools to improve yield and enable Industry 4.0 traceability. The system includes an industry-first paste temperature monitor, measured for proper paste viscosity and a roll height monitor that now measures both upper and lower limits. All data can be recorded for board traceability. This system will improve yield and reduce waste by ensuring proper paste viscosity to avoid bridging and voiding and eliminate insufficient or excess paste volumes.

Momentum II features new EdgeLoc II™ board clamping that uses a side-snugging system to remove the need for top clamps which interfere with the PCB to stencil contact. The result is optimal gasketing and more volumetrically consistent edge-to-edge prints. With EdgeLoc II, robust flippers engage to secure the board across the top edge ensuring board flatness then move out of the way once the board is firmly gripped from the side. EdgeLoc+ board clamping is also available which can change between edge and top clamping simply through software.

“We will be accepting orders for the Momentum II HiE and Elite models starting on January 1, 2020,” said Wayne Wang, MPM Business Manager. “We have received very positive feedback on the Momentum II from our beta customers and there has been much excitement about the release of this next generation printer.”



## *Electronic Assembly Equipment*

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*ITW EAE, a division of Illinois Tool Works, Inc., is the global leader in process knowledge, services and manufacture of capital equipment used in the printed circuit board assembly and semiconductor industries. The group brings together the world's leading brands of electronics assembly equipment: MPM Printers, Camalot Dispensers, Electrovert Cleaners and Soldering Solutions, Vitronics Soltec Soldering Solutions and Despatch Thermal Processing Technology. For more information visit [www.itweae.com](http://www.itweae.com).*